

REMARKS

INTRODUCTION

In accordance with the foregoing, claim 5 has been amended. Claims 1-4 and 12 have been cancelled. Claims 5, 10, 14 and 15 are pending and under consideration.

CLAIM REJECTIONS

Claim 1 was rejected under 35 USC 103(a) as being unpatentable over Ito et al. (US 6,410,904) (hereinafter "Ito") in view of the applicant's admitted prior art (hereinafter "AAPA").

Claims 2-4 were rejected under 35 USC 103(a) as being unpatentable over Ito in view of the AAPA and further in view of Miyazaki et al. (US 5,018,033) (hereinafter "Miyazaki").

Claims 5, 10, 12, 14 and 15 were rejected under 35 USC 103(a) as being unpatentable over Ito in view of the AAPA and further in view of Chun et al. (US 6,525,405) (hereinafter "Chun").

Claims 1-4

Claims 1-4 have been cancelled.

Claims 5, 10, 12, 14 and 15

Amended claim 5 recites: "...the drive chip is packaged with a mold resin in a state in which a semiconductor device is mounted on a lead frame... the drive chip further comprises a plurality of drive chip leads protruding outwardly from the mold resin." Support for this amendment may be found in at least original claim 12 and further in Figures 2 and 3 of the present application.

The Office Action relies on Chun to show the drive chip being packaged with a mold resin. Specifically, the Office Action relies on 4:41-4:47 and Figure 1.1 of Chun which discusses FIG. 1A illustrates, in cross-section, a first embodiment, a "near chip-size" leadless semiconductor packaging apparatus 1000 (i.e., where the packaging and external lead portions extend minimally beyond the plan-form area of a given chip) having packaging mold-lines 10 and a unique "stamped" and "bent" lead-frame 30 formed by "stamping" and "bending" a conductive material such as copper, with an effective solderable length 60 and effecting a bend 34, the unique stamped and bent lead-frame 30 being uniquely compressively retained by a mold 11. Chun, 4:41-4:50 and Figure 1A.

However, as discussed above, the packaging of Chun shown in is leadless. By contrast, claim 1 clearly recites that drive chip leads protrude outwardly from the mold resin. In addition to the leadless embodiment shown in Figure 1A, all of the other embodiments of Chun are also leadless. Accordingly, it is respectfully submitted that Chun cannot be combined with Itoh and the AAPA in order to arrive at the present invention as recited in claim 1.

It is well settled that prior art is interpreted not to teach an invention particularly when stated objectives of the prior art reinforced this interpretation. See WMS Gaming Inc. v. International Game Tech., 184 F.3d 1339, 51, USPQ2d 1385 (Fed. Cir. 1999). In the present case, Chun discusses leadless semiconductor packaging. By contrast, claim 1 recites drive chip leads protruding outwardly from a mold resin. Further, this deficiency in Chun is not cured by either the AAPA or Ito.

Claim 12 has been cancelled. Claims 10, 14 and 15 depend on claim 5 and are therefore believed to be allowable for at least the foregoing reasons.

Withdrawal of the foregoing rejection is requested.

CONCLUSION

There being no further outstanding objections or rejections, it is submitted that the application is in condition for allowance. An early action to that effect is courteously solicited.

Finally, if there are any formal matters remaining after this response, the Examiner is requested to telephone the undersigned to attend to these matters.

If there are any additional fees associated with filing of this Amendment, please charge the same to our Deposit Account No. 19-3935.

Respectfully submitted,

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